
RAM Technologies

RoHS CERTIFICATE OF COMPLIANCE

With exemptions

January 2010

This document certifies that the following models are in compliance with the Directive 2002/95/EC for reduction of hazardous substances RoHS.

The following substances cannot exceed the maximum concentrations listed below:

Substance	Max allowable concentration	Actual concentration
LEAD	< 0.1%	> 0.1%
MERCURY	< 0.1%	< 0.1%
CADMIUM	< 0.01%	< 0.01%
HEXAVALENT CHROMIUM	< 0.1%	< 0.1%
POLYBROMINATED BIPHENYLS	< 0.1%	< 0.1%
POLYBROMINATED DIPHENYL ETHERS	< 0.1%	< 0.1%

Under the Directive 2002/95/EC certain hazardous substances in electronics and electronics equipment (RoHS Directive) including solder are deemed compliant in accordance with the following exemptions listed in the annex of the RoHS directive:

6. Lead as an alloying element in steel containing up to 0,35% lead by weight, aluminum containing up to 0,4% lead by weight and as a copper alloy containing up to 4% lead by weight.
7. Lead in high melting temperatures type solders (i.e. tin-lead solder alloys containing more than 85% lead). Lead in solders for servers, storage and storage array systems . Lead in solders for network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications. Lead in ceramic parts (e.g. piezoelectric devices).

Models certified: PFC230PC, PFC230PCX, PFC310PCX, PFC400PCX,PFC600PCX
PFC175SFX, PFC200SFX, UPS8000, ML75 and ML75-12-5. Other products may apply
please consult factory.